

## N-Channel Enhancement Mode Power MOSFET

### Description

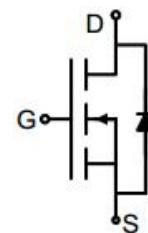
The GC11N65F uses advanced super junction technology and design to provide excellent  $R_{os(on)}$ , low gate charge and operation. This device is suitable for industry's AC-DC SMPS requirement for PFC, AC/DC power conversion, and industrial power application.

### General Features

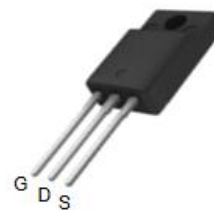
- $V_{DS}$  650V
- $I_D$  (at  $V_{GS} = 10V$ ) 11A
- $R_{DS(ON)}$  (at  $V_{GS} = 10V$ ) < 360m $\Omega$
- 100% Avalanche Tested
- RoHS Compliant

### Application

- Power switch
- DC/DC converters



Schematic diagram



TO-220F

### Ordering Information

Device	Package	Marking	Packaging
GC11N65F	TO-220F	GC11N65	50pcs/Tube

### Absolute Maximum Ratings $T_C = 25^\circ C$ , unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Continuous Drain Current	$I_D$	$T_C = 25^\circ C$	11
		$T_C = 100^\circ C$	7
Pulsed Drain Current (note1)	$I_{DM}$	33	A
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Power Dissipation	$P_D$	31.3	W
Single pulse avalanche energy (note2)	$E_{AS}$	125	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 150	$^\circ C$

### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	80	$^\circ C/W$
Maximum Junction-to-Case	$R_{thJC}$	4	$^\circ C/W$

Specifications $T_J = 25^\circ\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	650	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 650V, V_{GS} = 0V$	--	--	1	$\mu A$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	3.5	4.0	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5.5A$	--	330	360	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{GS} = 5V, I_D = 5.5A$	--	6	--	S
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = 400V,$ $f = 1.0MHz$	--	768	--	pF
Output Capacitance	$C_{oss}$		--	19	--	
Reverse Transfer Capacitance	$C_{rss}$		--	0.2	--	
Total Gate Charge	$Q_g$	$V_{DD} = 400V,$ $I_D = 5.5A,$ $V_{GS} = 10V$	--	21	--	nC
Gate-Source Charge	$Q_{gs}$		--	4.5	--	
Gate-Drain Charge	$Q_{gd}$		--	7	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 400V,$ $I_D = 5.5A,$ $R_G = 25\Omega$	--	42	--	ns
Turn-on Rise Time	$t_r$		--	20	--	
Turn-off Delay Time	$t_{d(off)}$		--	122	--	
Turn-off Fall Time	$t_f$		--	6.4	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	11	A
Body Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = 5.5A, V_{GS} = 0V$	--	--	1.2	V
Reverse Recovery Charge	$Q_{rr}$	$I_F = 5.5A, V_{GS} = 0V$ $di/dt = 100A/\mu s$	--	2.8	--	$\mu C$
Reverse Recovery Time	$T_{rr}$		--	280	--	ns

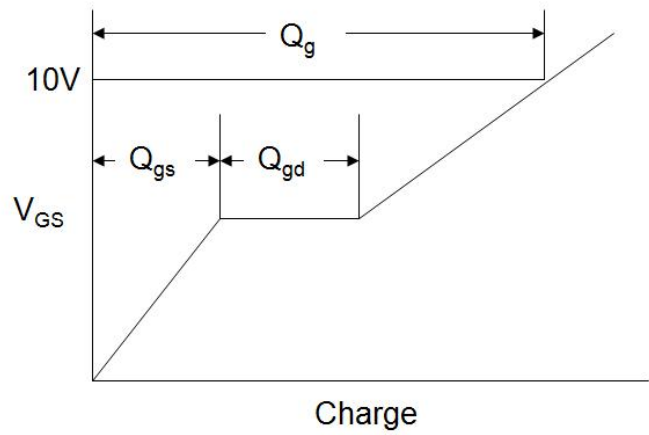
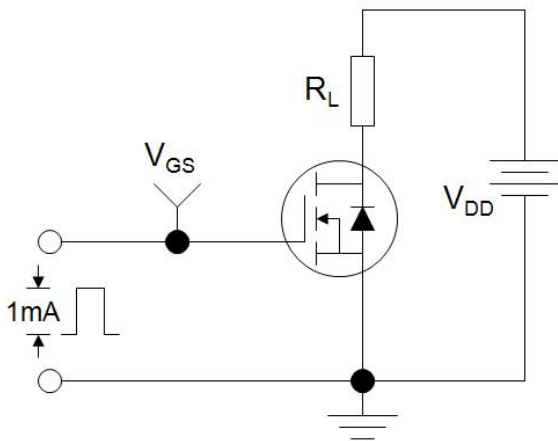
### Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition :  $T_J = 25^\circ\text{C}, V_{DD} = 50V, V_{GS} = 10V, L = 10mH, R_G = 25\Omega$

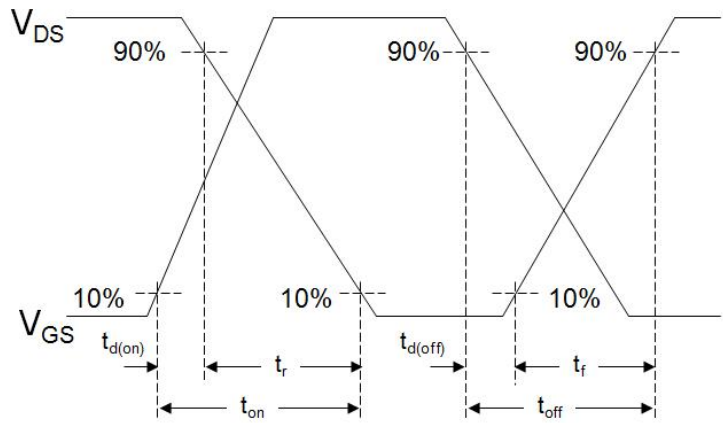
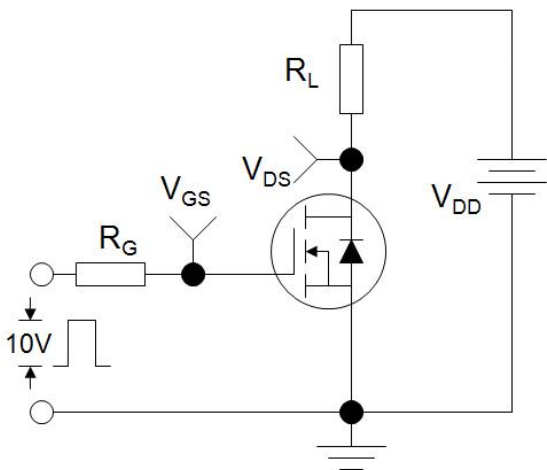
The table shows the minimum avalanche energy, which is 405mJ when the device is tested until failure

3. Identical low side and high side switch with identical  $R_G$

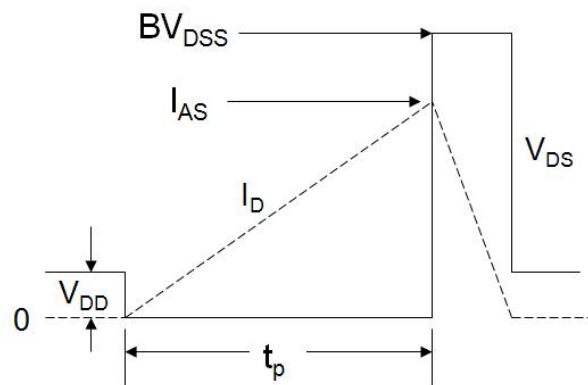
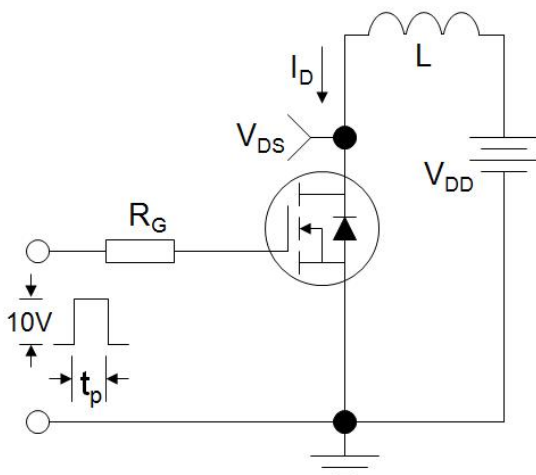
### Gate Charge Test Circuit



### Switch Time Test Circuit

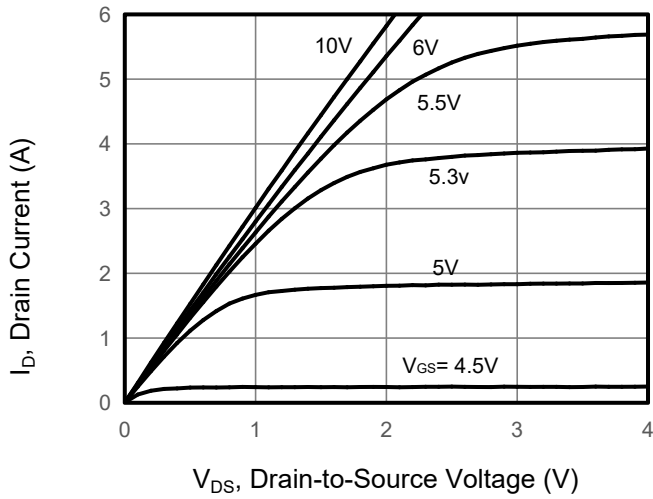


### EAS Test Circuit

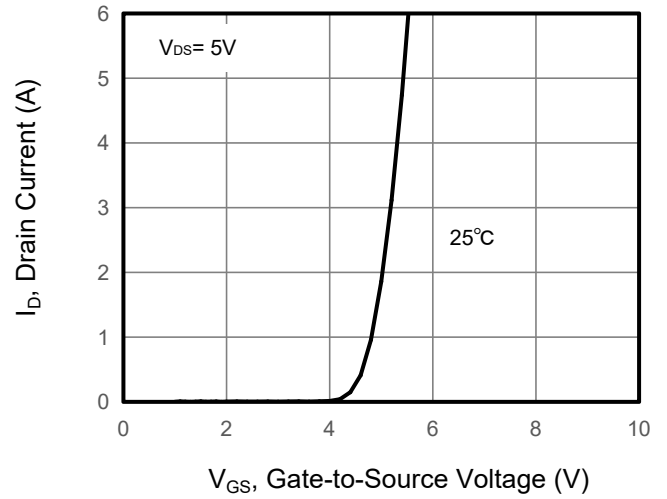


Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

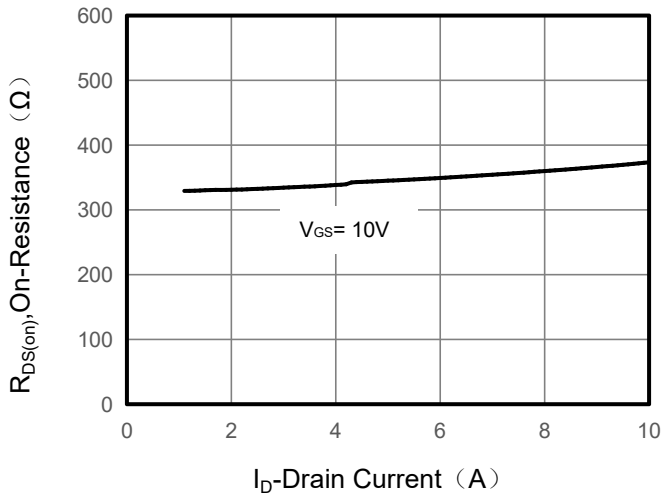
**Figure 1. Output Characteristics**



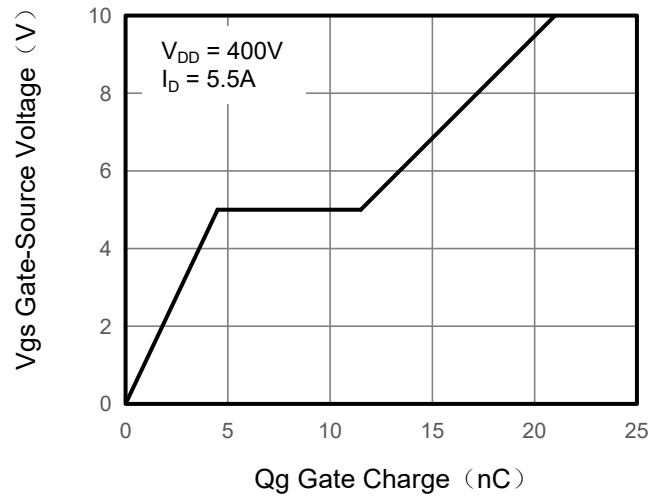
**Figure 2. Transfer Characteristics**



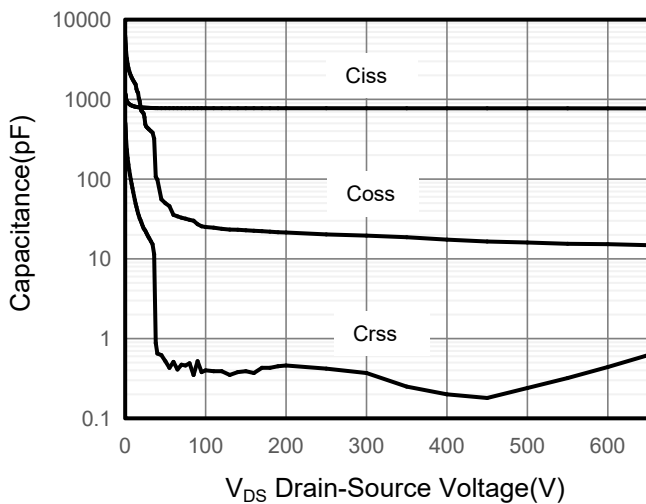
**Figure 3. Drain Source On Resistance**



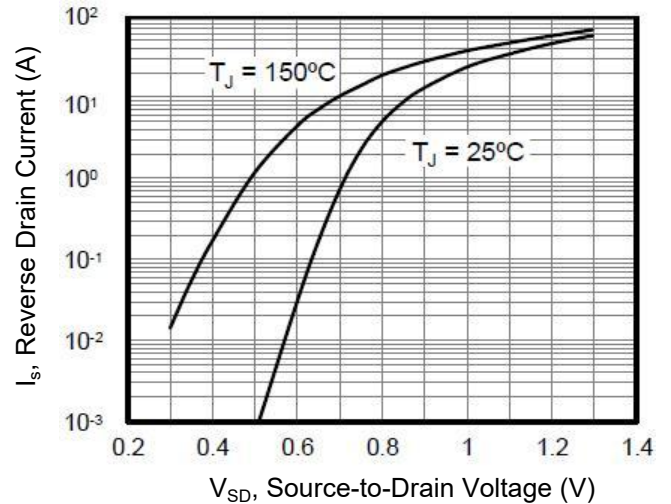
**Figure 4. Gate Charge**



**Figure 5. Capacitance**

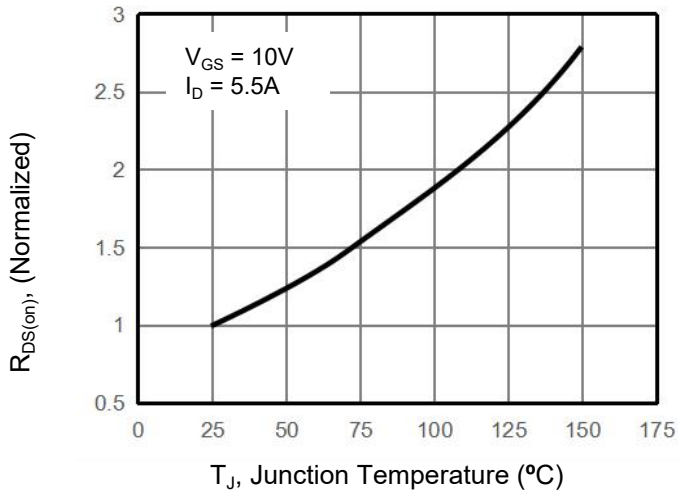


**Figure 6. Source-Drain Diode Forward**

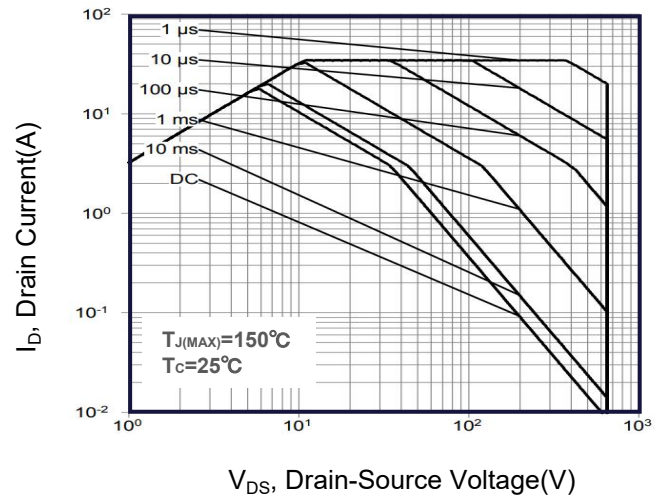


## Typical Characteristics $T_J = 25^\circ\text{C}$ , unless otherwise noted

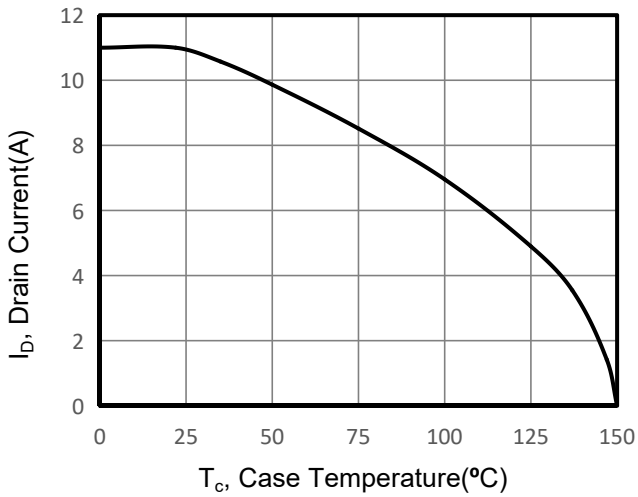
**Figure 7. Drain-Source On-Resistance**



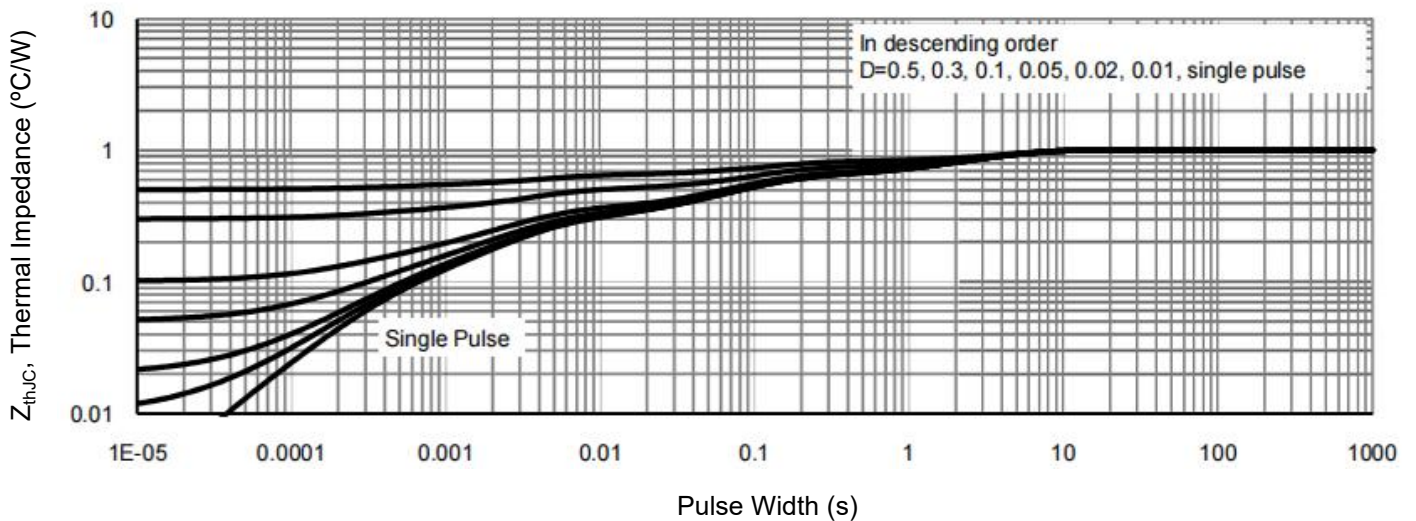
**Figure 8. Safe Operation Area**



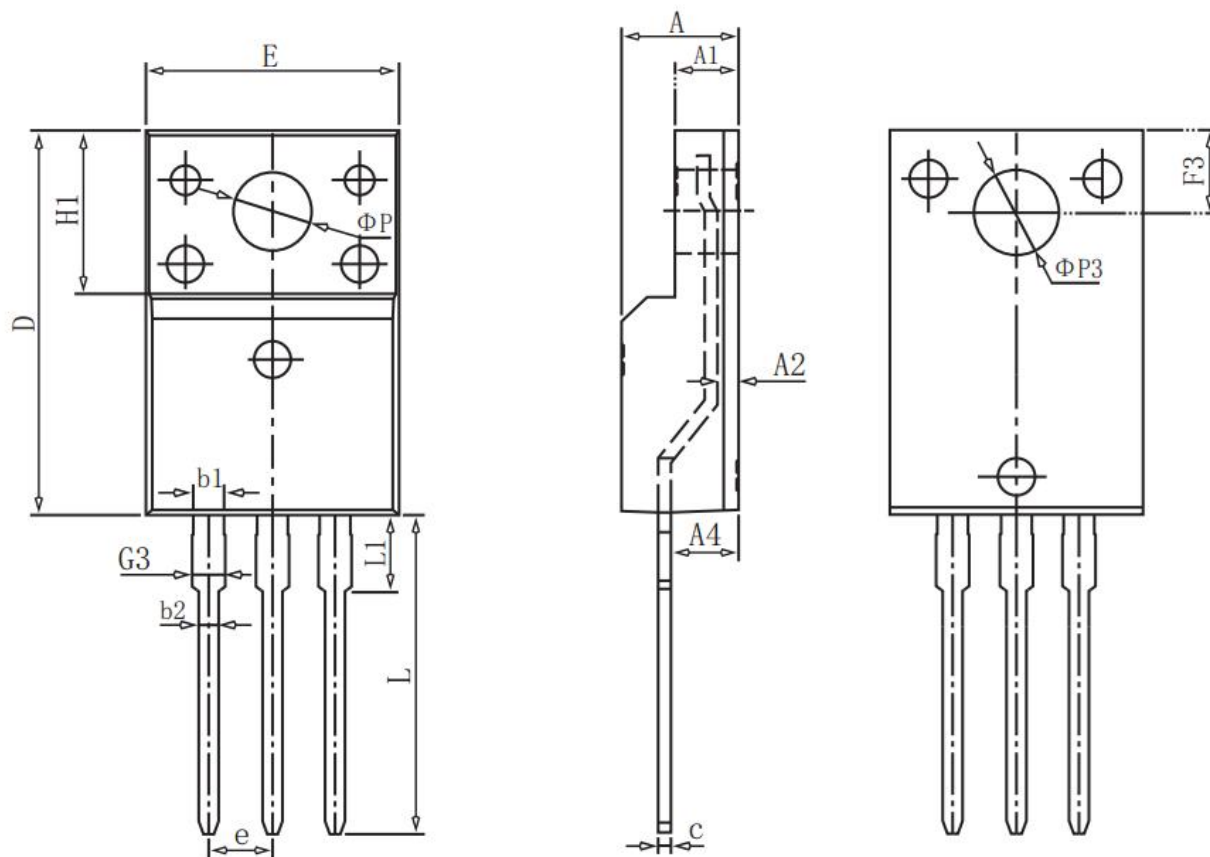
**Figure 9. Maximum Continuous Drain Current vs Case Temperature**



**Figure 10. Normalized Maximum Transient Thermal Impedance**



## TO-220F Package Information



### COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
E	10.00	10.20	10.40
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2	0.65	0.85	1.30
A4	2.55	2.75	2.95
c	0.40	0.50	0.65
D	15.57	15.87	16.17
H1	6.70REF		
e	2.54BSC		
$\Phi P$	3.183REF		
L	12.68	12.98	13.28
L1	3.25	3.45	3.65
$\Phi P3$	3.45REF		
F3	3.10	3.30	3.50
G3	1.10	1.30	1.50
$b_1$	1.05	1.20	1.35
$b_2$	0.70	0.80	0.92